



30V P-CHANNEL ENHANCEMENT MODE MOSFET

Totally Lead-Free & Fully RoHS compliant (Note 1 & 2) Halogen and Antimony Free. "Green" Device (Note 3) Qualified to AEC-Q101 Standards for High Reliability

Case Material: Molded Plastic, "Green" Molding Compound.

UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020

Terminal Connections Indicator: See diagram below Terminals: Finish — Matte Tin annealed over Copper lead

frame. Solderable per MIL-STD-202, Method 208 (C3)

Features and Benefits

Low On-Resistance Low Input Capacitance Fast Switching Speed

Mechanical Data

Case: SO-8

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	l _D max T _A = +25°C
-30V	7.5mΩ @ V _{GS} = -10V	-12A
-307	10.2mΩ @ V _{GS} = -4.5V	-10A

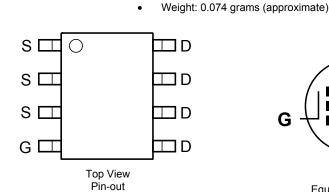
Description

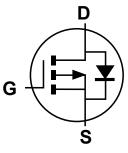
This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Backlighting
- Power Management Functions
- DC-DC Converters







Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMG4413LSS-13	SO-8	2500/Tape & Reel

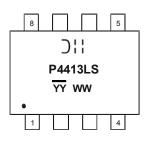
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

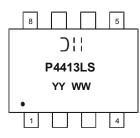
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Chengdu A/T Site



Shanghai A/T Site

)'! = Manufacturer's Marking
P4413LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)
YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units V		
Drain-Source Voltage	V _{DSS}	-30			
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	T _A = +25°C T _A = +70°C	I _D	-12 -10	А
	t<10s	T _A = +25°C T _A = +70°C	Ι _D	-22 -17	А
	Steady State	T _A = +25°C T _A = +70°C	ID	-10 -8	А
Continuous Drain Current (Note 6) V_{GS} = -4.5	t<10s	T _A = +25°C T _A = +70°C	ID	-18 -14	А
Pulsed Drain Current (10µs pulse, duty cycle = 1	I _{DM}	-100	А		
Maximum Body Diode continuous Current			ls	-4	А

Thermal Characteristics

Characteristic	Symbol	Value	Units		
Total Dower Discinction (Note 5)	T _A = +25°C	D	1.7	W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	1.1		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{0JA}	74	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	RθJA	22		
Total Power Dissipation (Note 6)	T _A = +25°C	Р	2.2	w	
Total Power Dissipation (Note 6)	T _A = +70°C	PD	1.4	vv	
Thermal Desistance, Junction to Ambient (Note 6)	Steady State	56			
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	R _{0JA}	17	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Steady State	R _{θJC}	2.5		
Operating and Storage Temperature Range		T _{J.} T _{STG}	-55 to 150	°C	

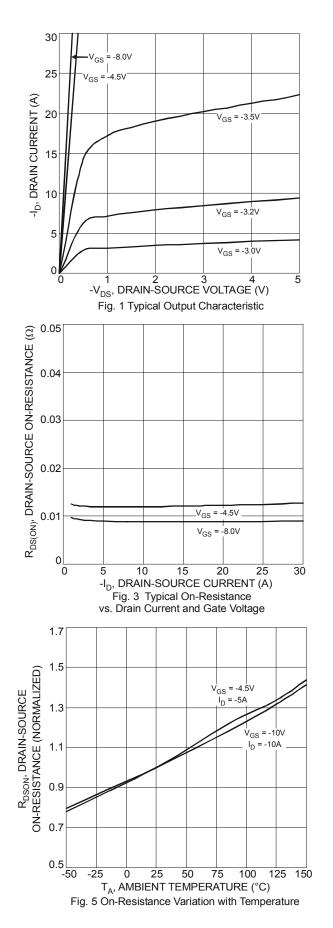
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

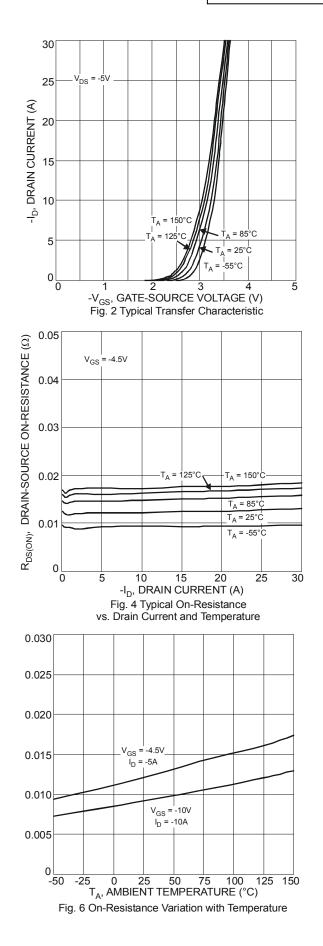
Characteristic	Symphol	Min	Turn	Max	Unit	Test Condition
	Symbol	Min	Тур	wax	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	51					
Drain-Source Breakdown Voltage	BV _{DSS}	-30			V	V_{GS} = 0V, I_{D} = -250µA
Zero Gate Voltage Drain Current	I _{DSS}		—	-1	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}			±1	μA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-1.1	1.6	-2.1	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Static Drain-Source On-Resistance		_	6.3	7.5	6	V _{GS} = -10V, I _D = -13A
Static Drain-Source On-Resistance	R _{DS(ON)}	_	7.9	10.2	mΩ	V_{GS} = -4.5V, I_{D} = -10A
Forward Transconductance	g fs	_	26		S	V _{DS} = -15V, I _D = -13A
Diode Forward Voltage	V _{SD}	_	-0.7	-1.0	V	V _{GS} = 0V, I _S = -2.7A
DYNAMIC CHARACTERISTICS (Note 8)	•					·
Input Capacitance	Ciss	_	4965		pF	
Output Capacitance	C _{oss}	_	1487		pF	V _{DS} = -15V, V _{GS} = 0V f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	711	—	pF	
Gate Resistance	R _G	_	7.3	_	Ω	V _{DS} = 0V, V _{GS} = 0V f = 1.0MHz
SWITCHING CHARACTERISTICS (Note 8)			_			
Total Gate Charge	Q _G	_	46			V _{DS} = -15V, V _{GS} = -5V I _D = -13A
Gate-Source Charge	Q _{GS}	_	17		nC	
Gate-Drain Charge	Q _{GD}	_	16	—		
Turn-On Delay Time	t _{d(on)}	_	15	_		V _{DS} = -15V, V _{GS} = -10V,
Rise Time	tr	_	9	—	ns	
Turn-Off Delay Time	t _{d(off)}	_	160	—	115	I_{D} = -1A, R_{G} = 6.0 Ω
Fall Time	t _f	_	66			

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

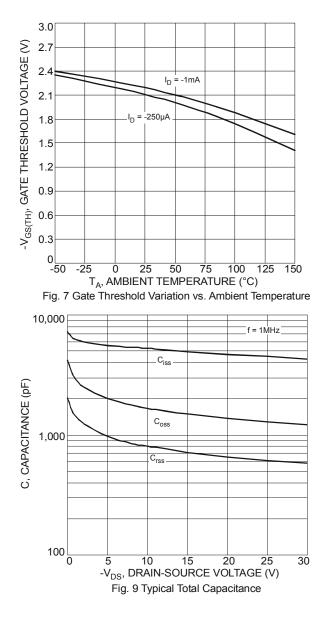
Notes:

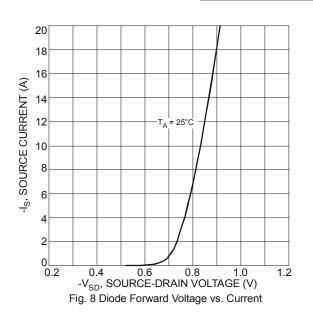






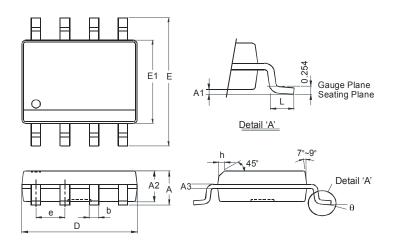






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

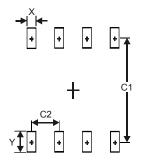


SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
E	5.90	6.10		
E1	3.85	3.95		
e	1.27 Typ			
h	-	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				



Suggested Pad Layout

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27

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